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<table border="1"><tr><td colspan="2">NAME OF INVENTOR(S): Signey</td><td colspan="2">RECEIPT DATE & SERIAL NO.: Serial No.: 09/975,219 Filing Date: 10/11/2001</td></tr><tr><td colspan="2">TITLE OF INVENTION: METHOD AND SYSTEM FOR CUTTING INTEGRATED CIRCUIT PACKAGES</td><td colspan="2"></td></tr><tr><td>TI FILE NO.: TI-27954</td><td>DEPOSIT ACCT. NO.: 20-0668</td><td colspan="2"></td></tr><tr><td colspan="2">FAXED: 9-29-05 DUE: 08/09/2005 ATTY/SEC'Y: WDS/rlc</td><td colspan="2"></td></tr></table>		NAME OF INVENTOR(S): Signey		RECEIPT DATE & SERIAL NO.: Serial No.: 09/975,219 Filing Date: 10/11/2001		TITLE OF INVENTION: METHOD AND SYSTEM FOR CUTTING INTEGRATED CIRCUIT PACKAGES				TI FILE NO.: TI-27954	DEPOSIT ACCT. NO.: 20-0668			FAXED: 9-29-05 DUE: 08/09/2005 ATTY/SEC'Y: WDS/rlc			
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